

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
TENG-CHUN TSAI	06/06/2014
LI-TING WANG	06/09/2014
DE-FANG CHEN	06/06/2014
CHENG-TUNG LIN	06/06/2014
CHIH-TANG PENG	06/06/2014
CHIEN-HSUN WANG	06/06/2014
BING-HUNG CHEN	06/06/2014
HUAN-JUST LIN	06/06/2014
YUNG-CHENG LU	06/06/2014
RECEIVING PARTY DATA	
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.
Street Address:	NO.8, LI-HSIN RD. 6, SCIENCE BASED INDUSTRIAL PARK
City:	HSINCHU
State/Country:	TAIWAN
Postal Code:	300
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16921015
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ATTORNEY DOCKET NUMBER:	095714-1214

NAME OF SUBMITTER:	TAKASHI SAITO
SIGNATURE:	/Takashi Saito/
DATE SIGNED:	07/06/2020
Total Attachments: 2 source=assignment for filing from parent#page1.tif source=assignment for filing from parent#page2.tif	

JOINT

ASSIGNMENT

WHEREAS, WE, TENG-CHUN TSAI, LI-TING WANG, DE-FANG CHEN, CHENG-TUNG LIN, CHIH-TANG PENG, CHIEN-HSUN WANG, BING-HUNG CHEN, HUAN-JUST LIN, and YUNG-CHENG LU citizen of the Republic of China, having the mailing addresses listed as below.

TENG-CHUN TSAI having a mailing address of 11F, No.188, Guanxin W. St., East Dist., Hsinchu City, Taiwan residing at Hsinchu City, Taiwan;

LI-TING WANG having a mailing address of 11F., No. 39, Ln. 19, Guanxin Rd., East Dist., Hsinchu City 300, Taiwan residing at Hsinchu City, Taiwan;

DE-FANG CHEN having a mailing address of 6F.-1, No. 375, Sec. 2, Gongdao 5th Rd., East Dist., Hsinchu City 300, Taiwan residing at Hsinchu City, Taiwan;

CHENG-TUNG LIN having a mailing address of 5F., No. 6, Alley 39, Lane 152, Sec. 2, Jhongsing Rd., Jhudong Township, Hsinchu County 310, Taiwan residing at Hsinchu County, Taiwan;

CHIH-TANG PENG having a mailing address of 10F.-3, No. 85, Sec. 2, Jiafeng 6th Rd., Zhubei City, Hsinchu County 302, Taiwan residing at Hsinchu County, Taiwan;

CHIEN-HSUN WANG having a mailing address of No. 42, Ln. 173, Minxiang St., Hsinchu City 300, Taiwan residing at Hsinchu City, Taiwan;

BING-HUNG CHEN having a mailing address of 10F-1, No. 65, Ho-Ping Street, San-Xia Dist., New Taipei City, Taiwan residing at New Taipei City, Taiwan;

HUAN-JUST LIN having a mailing address of No. 126, Lane 228, Wuling Rd., Hsinchu City 300, Taiwan residing at Hsinchu City, Taiwan;

YUNG-CHENG LU having a mailing address of 8F-12, No. 2, Lane 62, Changchun St., Hsinchu City, Taiwan residing at Hsinchu City, Taiwan,

ASSIGNORS, are the inventors of the invention in "METHOD OF FORMING ISOLATION LAYER" for which we have executed an application for a Patent of the United States

- which is executed on even date herewith or [DATE]
- which is identified by Jones Day docket no. 181877-625126
- which was filed on _____, 2014, Application No. _____.
- We hereby authorize and request attorney(s) at Jones Day, to insert here in parentheses (Application number _____, filed _____) the filing date and application number of said application when known.

and WHEREAS, Taiwan Semiconductor Manufacturing Company Limited, a corporation organized and existing under the laws of the Republic of China, and having an office for the transaction of business at No. 8, Li-Hsin Rd. VI, Hsinchu Science Park, Hsinchu, Taiwan, ASSIGNEE, is desirous of obtaining our entire right, title and interest in, to and under the said invention and the said application:

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, we, the said ASSIGNORS, have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said ASSIGNEE, its successors, legal representatives and assigns, our entire right, title and interest in, to and under the said invention, and the said United States application and all divisions, renewals and continuations thereof, and all Patents of the United States which may be granted thereon and all reissues and extensions thereof; and all applications for industrial property protection, including, without limitation, all applications for patents, utility models, and designs which may be filed for said invention in any country or countries foreign to the United States, together with the right to file such applications and the right to claim for the same the priority rights derived from said United States application under the Patent Laws of the United States, the International Convention for the Protection of Industrial Property, or any other international agreement or the domestic laws of the country in which any such application is filed, as may be applicable; and all forms of industrial property protection, including, without limitation, patents, utility models, inventors' certificates and designs which may be granted for said invention in any country or countries foreign to the United States and all extensions, renewals and reissues thereof; and all right to sue for infringement including past infringement.

AND WE HEREBY authorize and request the Commissioner for Patents and any Official of any country or countries foreign to the United States, whose duty it is to issue patents or other evidence or forms of industrial property protection on applications as aforesaid, to issue the same to the said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant and agree that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to the said ASSIGNEE, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing, reissue and foreign applications, make all rightful oaths, and generally do everything possible to aid the said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper protection for said invention in all

countries.

IN TESTIMONY WHEREOF, We hereunto set our hands and seals the day and year set opposite our respective signatures.

Date 06/06/2014, 2014 Teng-Chun Tsai L.S.
TENGG-CHUN TSAI

Date 06/09/2014, 2014 Li-Ting Wang L.S.
LI-TING WANG

Date 6/6, 2014 De Fang Chen L.S.
DE-FANG CHEN

Date 06/06/2014, 2014 Cheng-Tung Lin L.S.
CHENG-TUNG LIN

Date 06/06/2014, 2014 Chih-Tang Peng L.S.
CHIH-TANG PENG

Date 06/06/2014, 2014 Chien-Hsun Wang L.S.
CHIEN-HSUN WANG

Date 06/06/2014, 2014 Bing-Hung Chen L.S.
BING-HUNG CHEN

Date 06/06/2014, 2014 Huan-Just Lin L.S.
HUAN-JUST LIN

Date 6/6, 2014 Yung-Cheng Lu L.S.
YUNG-CHENG LU